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SEMICONDUCTOR DEVICE

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PURPOSE: To provide a semiconductor device prevented from generating the exfoliations of a resin from a die pad in a chain-reacting way and from generating the cracks of the resin, by improving the adhesiveness of the resin to the die pad in the corner of the die pad wherein the exfoliations are especially apt to occur, in the resin-sealed semiconductor device including a semiconductor chip die-bonded to the die pad.

CONSTITUTION: On each sidewall of a die pad 1, a recessed part 11 or a protruding part or the combination thereof is formed. Then, a resin 6 is made to eat into the recessed part 11 or to cover completely the protruding part, and concurrently, the effect of the difference between the thermal expansion coefficients of the resin 6 and the die pad 1 is made small by covering thin protruding parts 12 of the die pad 1 with the resin 6. Thereby, the adhesiveness of the resin 6 to the die pad 1 is improved.